162162

G00002

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a method for visual inspection of semiconductor packages in a semiconductor package manufacturing apparatus including a table on which semiconductor packages to be inspected are mounted, a picker having a plurality of pick-up members with an adjustable gap therebetween for fixing the semiconductor packages, and a camera photographing the semiconductor package picked-up by the picker. The method includes picking up some of the semiconductor packages from the table by the picker under a condition in which a gap between the pick-up members is a first pitch, adjusting the gap between the pick-up members of the picker to a second pitch which is less than the first pitch, and photographing the semiconductor packages picked-up by the picker using the camera while the picker moves relative to the camera.